

448 Series Fuse



Agency Approvals

Agency	Agency File Number	Ampere Range
	E10480	0.062A - 15A
	29862	0.062A - 15A
	NBK030205-E10480A NBK030205-E10480B NBK101105-E184655	1A - 1.6A 2A - 5A 6.3A - 10A

Electrical Characteristics for Series

% of Ampere Rating	Ampere Rating	Opening Time
100%	0.062A -15	4 hours, Minimum
200%	0.062A -10	5 sec., Maximum
	12 -15	20 sec., Maximum

Description

The lead-free Nano² SMF Fuse is a very small, square surface mount fuse that is RoHS compliant, Halogen Free and 100% lead-free. This product is fully compatible with lead-free solder alloys and higher temperature profiles associated with lead-free assembly.

Features

- RoHS compliant, Lead-free and Halogen Free
- Very fast-acting
- Small size
- Wide range of current rating available (0.062A to 15A)
- Wide operating temperature range
- UL Recognized to UL/CSA/NMX UL 248-1 and UL/CSA/NMX UL 248-14
- Conforms to DENAN's Appendix 3

Applications

- Notebook PC
- LCD/PDP TV
- LCD monitor
- LCD/PDP panel
- LCD backlight inverter
- Portable DVD player
- Power supply
- Networking
- PC server
- Cooling fan system
- Storage system
- Telecom system
- Wireless basestation
- White goods
- Game console
- Office Automation equipment
- Battery charging circuit protection
- Industrial equipment

Additional Information



Datasheet



Resources



Samples

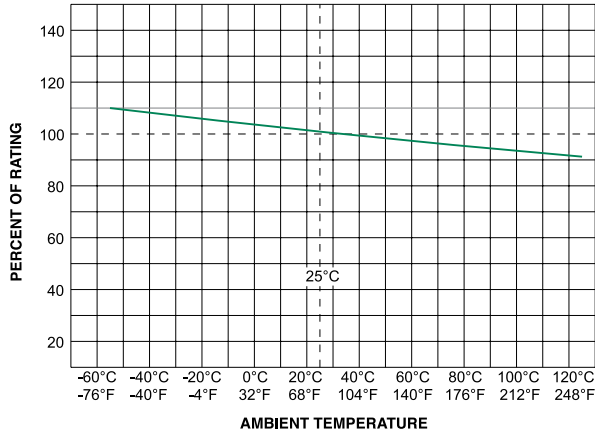
Electrical Specifications by Item

Ampere Rating (A)	Amp Code	Max Voltage Rating (V)	Interrupting Rating	Nominal Cold Resistance (Ohms)	Nominal Melting I ² t (A ² sec)	Agency Approvals		
								
0.062	.062	125	50A @125VAC/ VDC 300A @32 VDC PSE: 100A @100VAC	5.50	0.00023	x	x	
0.080	.080	125		4.42	0.00043	x	x	
0.100	.100	125		2.90	0.00082	x	x	
0.125	.125	125		2.58	0.00130	x	x	
0.160	.160	125		1.76	0.00280	x	x	
0.200	.200	125		1.65	0.00380	x	x	
0.250	.250	125		0.95	0.01520	x	x	
0.315	.315	125		0.7015	0.02650	x	x	
0.375	.375	125		0.6155	0.02400	x	x	
0.400	.400	125		0.4895	0.04160	x	x	
0.500	.500	125		0.3800	0.10000	x	x	
0.630	.630	125		0.3125	0.121	x	x	
0.750	.750	125		0.2290	0.206	x	x	
0.800	.800	125		0.1907	0.272	x	x	
1.00	.001	125		0.08630	0.441	x	x	x
1.25	1.25	125		0.06619	0.900	x	x	x
1.50	01.5	125		0.06514	0.900	x	x	x
1.60	01.6	125		0.06261	1.122	x	x	x
2.00	002.	125		0.03529	0.812	x	x	x
2.50	02.5	125		0.02934	1.156	x	x	x
3.00	003.	125		0.02445	1.720	x	x	x
3.15	3.15	125		0.02300	1.810	x	x	x
3.50	03.5	125		0.02100	2.300	x	x	x
4.00	004.	125		0.01577	3.970	x	x	x
5.00	005.	125		0.01531	4.490	x	x	x
6.30	06.3	125		0.01044	12.10	x	x	x
7.00	007.	125		0.00900	13.92	x	x	x
8.00	008.	125		0.00780	18.33	x	x	x
10.00	010.	125	35A @125 VAC 50A @125 VDC 300A @32 VDC PSE: 100A @100VAC	0.00700	28.00	x	x	x
12.00	012.	85	50A @65 VAC/ VDC	0.00533	47.59	x	x	
15.00	015.	85	300A @24 VDC 200A @85 VDC	0.00394	78.4	x	x	

Notes:

- I²t calculated at 8ms.
- Resistance is measured at 10% of rated current, 25°C

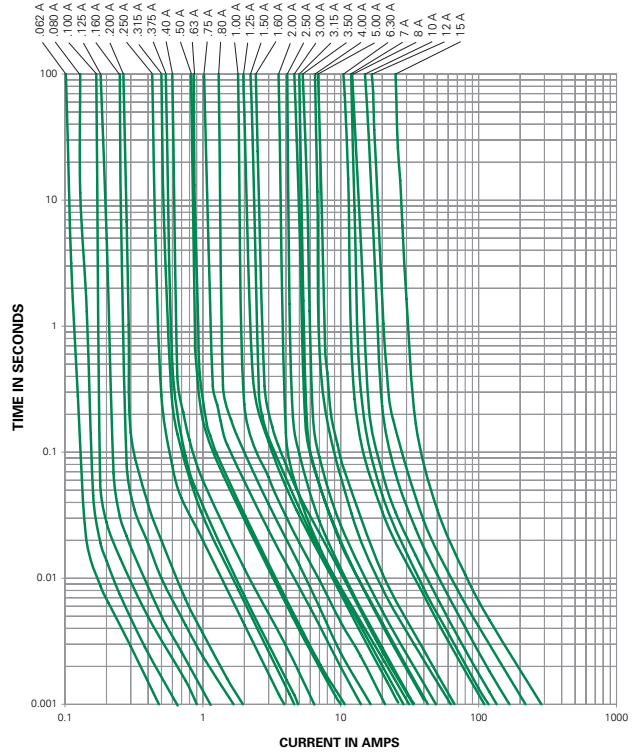
Temperature Re-rating Curve



Note:

1. Rerating depicted in this curve is in addition to the standard derating of 25% for continuous operation.

Average Time Current Curves



Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (Min to Max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		5°C/second max.
$T_{s(max)}$ to T_L - Ramp-up Rate		5°C/second max.
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max.
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

Wave Soldering Parameters 260°C Peak Temperature, 10 seconds max.

